



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0301-02** DATE: 4/2/2003
 Product Affected:
 IDT72V2103, IDT72V2113, IDT72V36100, IDT72V36110
 IDT72V295, IDT72V2105, IDT72V2101, IDT72V2111
 Date Effective: 7/2/2003

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark
 Back Mark Please see Description section below
 Date Code for details
 Other

Contact: Dasharath Patel
 Title: Quality Assurance Manager Attachment: Yes No
 Phone #: (408) 330-1488
 Fax #: (408) 330-1450 Samples: Available now
 E-mail: Dasharath.Patel@idt.com

DESCRIPTION AND PURPOSE OF CHANGE:

Die Technology Die shrink and process change from CEMOS 8 to CEMOS 11.5
 Wafer Fabrication Process
 Assembly Process Means of identifying material:
 Equipment CEMOS 8: Y-Step Date Code: Yyyww
 Material CEMOS 11.5: X-Step Date Code: XByyww
 Testing
 Manufacturing Site yy: Year
 Data Sheet ww: Work Week
 Other

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification summary

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ **Approval for shipments prior to effective date.**
 Name/Date: _____ E-Mail Address: _____
 Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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PCN Type: Die Shrink and Process Change

Data Sheet Change: None

Detail of Change: Die shrink and process technology change (CEMOS 8 to CEMOS 11.5) for the following products:

IDT72V2103, IDT72V2113, IDT72V36100, IDT72V36110
IDT72V295, IDT72V2105, IDT72V2101, IDT72V2111

Conversion Schedule (Estimated)

Samples	Available upon request
Production Shipments	7/2/2003



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Qualification Plan: QFI-02-17

Test Vehicle: IDT72V36110

Test Description/Condition	Test Methods	SS /# Fails	Test Results
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	45 / 0
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45/0	45 / 0
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	45 / 0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	77/0	77 / 0
Latch-Up Immunity (+ - I and V stress, + - 100mA Trigger)	EIA/JESD 78	10/0	10 / 0
ESD Human Body Model	MIL-STD-883, Method 3015	9/0	9 / 0
ESD Charge Device Model	JESD22-C101	6/0	6 / 0

Characterization Data:

Characterization Data is available upon request.